



TE Internal #: 1-1554653-1
 LGA Sockets, LGA 2011, Board-to-Board, 2011 Position, Gold,
 Contact Mating Area Plating Material Thickness 30 µin, 1.02mm [.04in] Centerline

[View on TE.com >](#)

Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 2011 SOCKETS



IC Socket Type: **LGA 2011**

Connector System: **Board-to-Board**

Number of Positions: **2011**

Contact Mating Area Plating Material: **Gold**

Contact Mating Area Plating Material Thickness: **[30 µin]**

[All LGA 2011 SOCKETS \(6\)](#)

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Number of Positions	2011
Grid Spacing	1.016 x .8814 mm [.040 x .0347 in]

Body Features

Frame Style	Square
Plating Material	Gold
Plating Thickness	30 µin

Contact Features

Contact Base Material	Copper Alloy
IC Socket Type	LGA 2011



Contact Mating Area Plating Material	Gold
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	30 µin
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Contact Current Rating (Max)	.5 A
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Mechanical Attachment

Heat Sink Attachment	Without
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PCB Mounting Style	Surface Mount Solder Ball
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Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	1.02 mm [.04 in]
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Housing Material	High Temperature Thermoplastic
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Housing Color	Black
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Usage Conditions

Operating Temperature Range	-25 – 100 °C [-13 – 212 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Tray Color	Blue
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Packaging Method	Tray
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Other

Comment	Lead-Free Solderball
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
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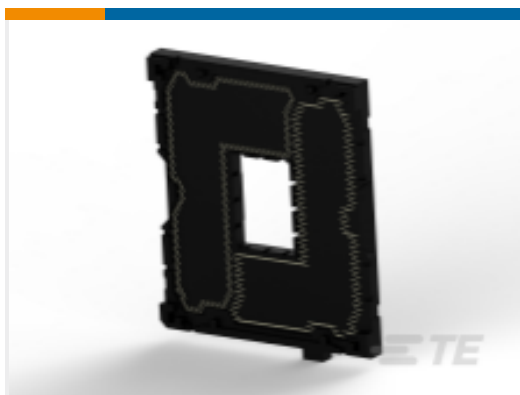
Halogen Content Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # CAT-L59017-A68
LGA 2011 SOCKETS



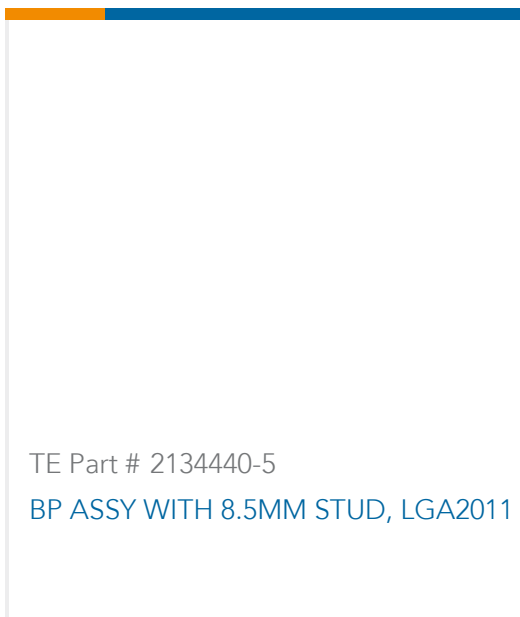
TE Part # CAT-L59017-A68H
LGA 2011 Hardware: ILM Assembly



TE Part # 2134440-3
BP ASSY, LGA2011,9MM STUD



TE Part # 1-2134784-1
ILM DUST COVER LGA2011

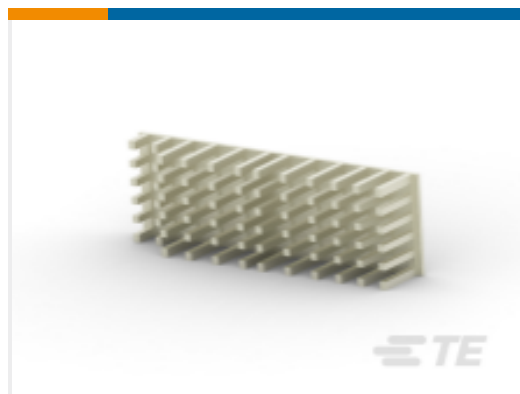


TE Part # 2134440-5
BP ASSY WITH 8.5MM STUD, LGA2011

Customers Also Bought



TE Part #1-338084-3
RJ22 Connectors



TE Part #1367500-1
XFP Heat Sink



TE Part #1888247-1
SFP Connectors



TE Part #1892714-2
MBXL R/A HDR 2P



Documents

Product Drawings

[SOCKET ASSY LGA2011, 0.76Au](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_1-1554653-1_H.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-1554653-1_H.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-1554653-1_H.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[6-1773461-9_LGA_2011_SOCKET](#)

English

Product Specifications

[Application Specification](#)

English

Product Environmental Compliance

[MD_1-1554653-1_04132015514_dmtec](#)

1-1554653-1

LGA Sockets, LGA 2011, Board-to-Board, 2011 Position, Gold, Contact Mating Area
Plating Material Thickness 30 μ in, 1.02mm [.04in] Centerline



English

[MD_1-1554653-1_04132015514_dmtec](#)

English